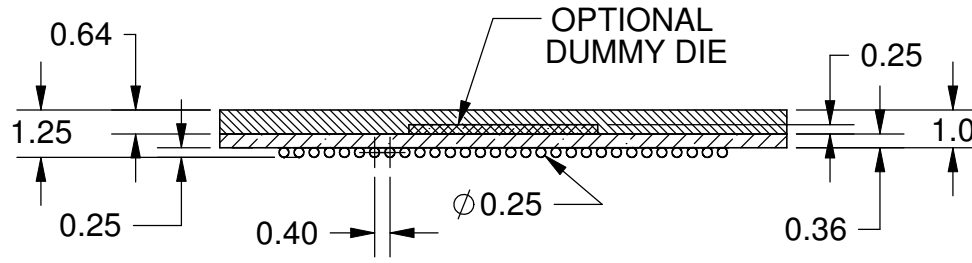
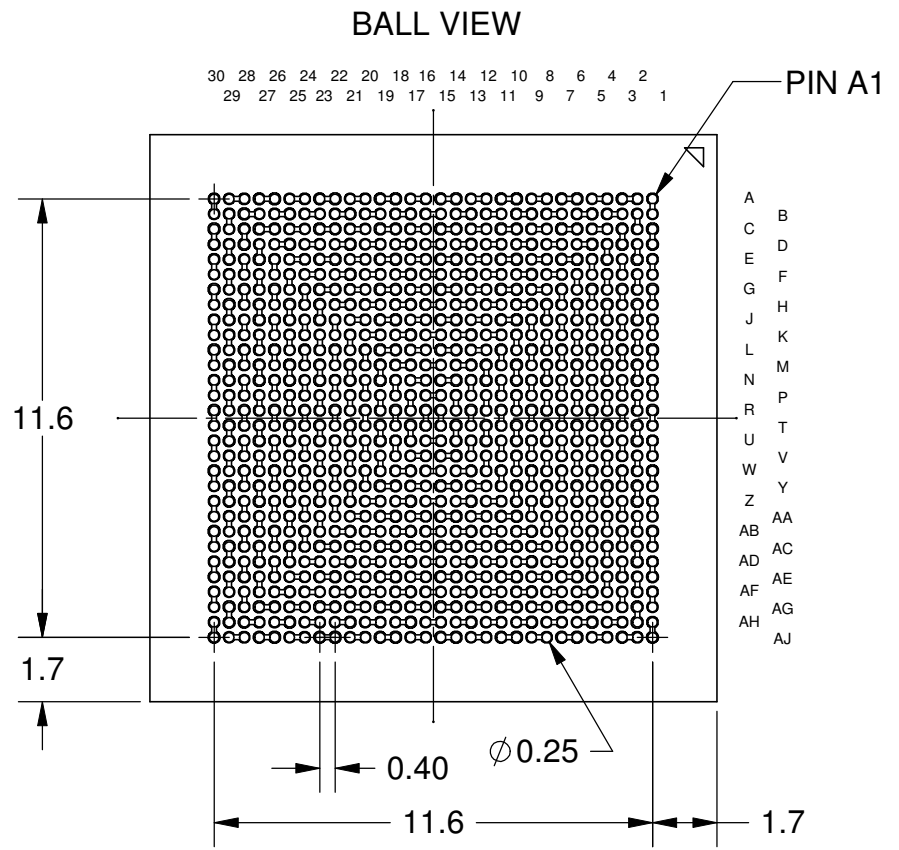
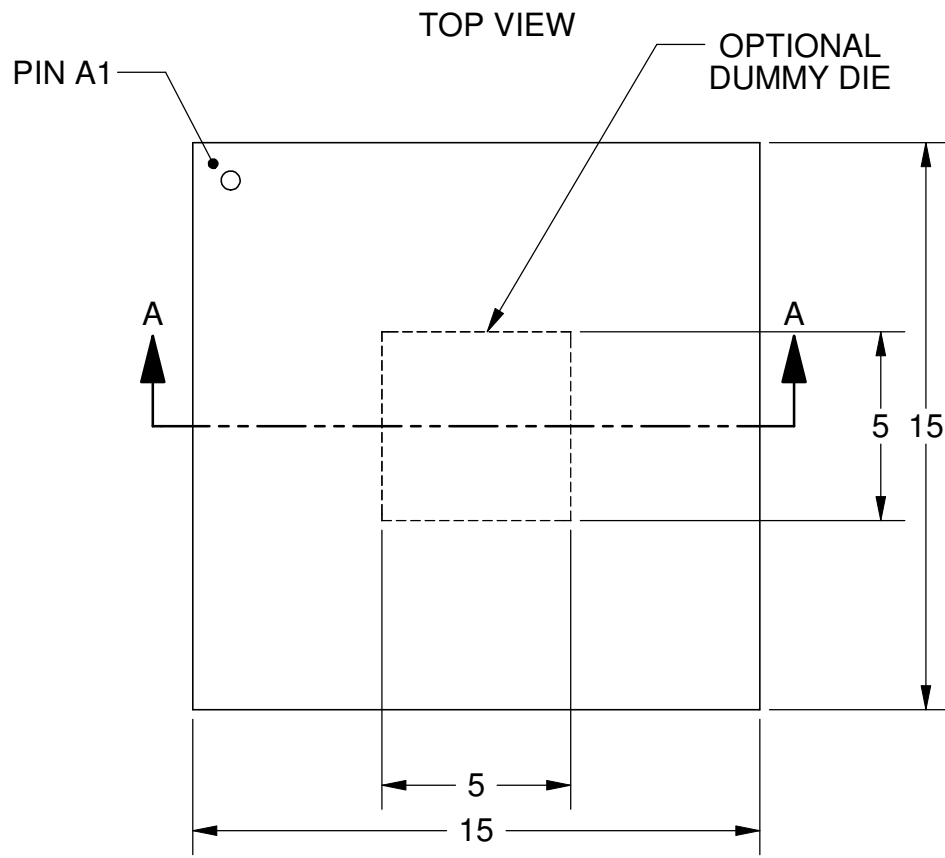



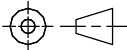
REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED



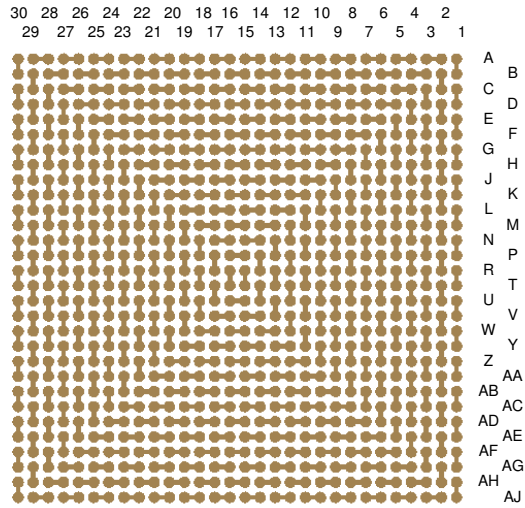
SECTION A-A

- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm [8.7 MIL].
 - 5) PAD Cu DIAMETER: 0.305mm [12 MIL].
 - 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

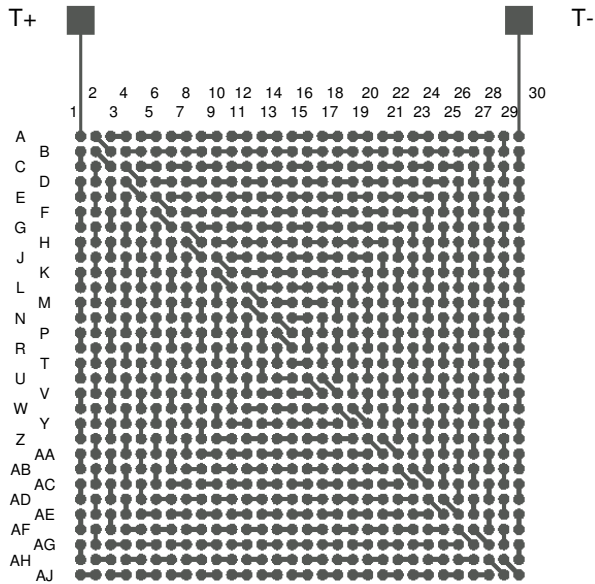
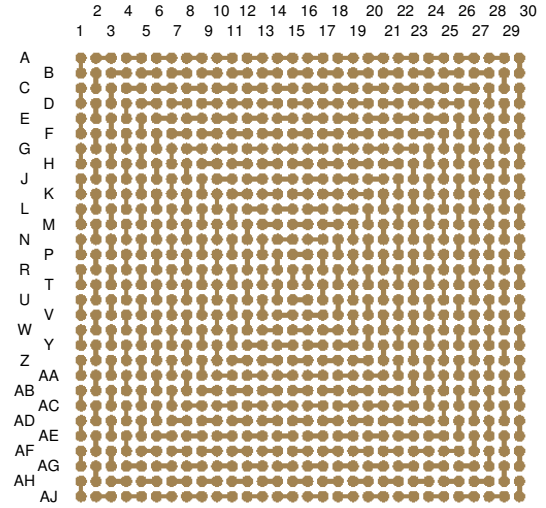
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA900T.4C-DC309	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA900T.4C-DC309D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA900T.4-DC309	Sn63/Pb37	NO	NO	NO
BGA900T.4-DC309D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE				
X.XX	+/- 0.01	DRAWN J. Hines		9/16/2010				
X.XXX	+/- 0.005	ENG						
X.XXXX	+/- 0.0005	MFG			TITLE			
ANGLES +/- 0.5°		QA			BGA900T.4-DC309 DAISY CHAIN DUMMY			
ALL DIMENSIONS IN ☐ INCHES ☒ MILLIMETERS		CUST				SCALE		
THIRD ANGLE PROJECTION		REVISED			5:1	SIZE	DRAWING NO.	REV
					A	543091	A	
					DO NOT SCALE DRAWING		SHEET 1 OF 2	

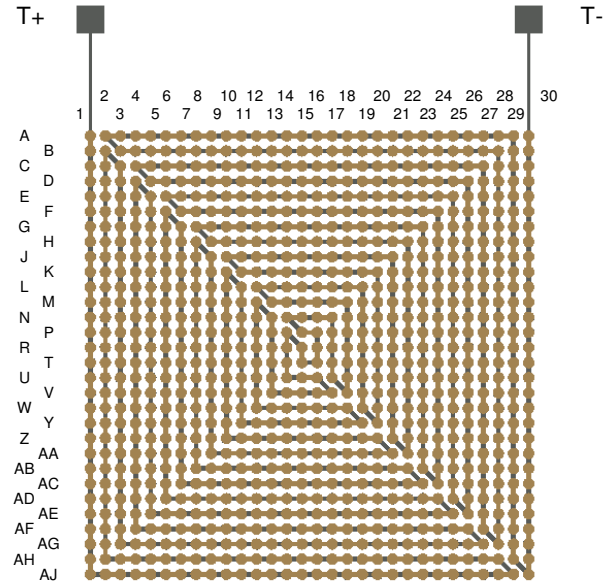
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm [12 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.22mm [8.7 MIL].

TopLine ®			
TITLE BGA900T.4-DC309 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
5:1	A	543091	A
DO NOT SCALE DRAWING			SHEET 2 OF 2